Integrated Device Technology, Inc.

FAST CMOS 18-BIT UNIVERSAL BUS TRANSCEIVER WITH 3-STATE OUTPUTS

IDT74FCT16601AT/CT/ET
IDT74FCT162601AT/CT/ET
PRODUCT PREVIEW

FEATURES:

- **Common features:**
  - 0.5 MICRON CMOS Technology
  - **High-speed, low-power CMOS replacement for ABT functions**
  - **Typical $t_{SK(o)}$ (Output Skew) < 250ps**
  - **Low input and output leakage ≤1μA (max.)**
  - ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)
  - Packages include 25 mil pitch SSOP, 19.6 mil pitch TSSOP, 15.7 mil pitch TVSOP and 25 mil pitch Cerpack
  - Extended commercial range of -40°C to +85°C
  - V_{CC} = 5V ±10%
- **Features for FCT16601AT/CT/ET:**
  - High drive outputs (-32mA I_{OH}, 64mA I_{OL})
  - Power off disable outputs permit “live insertion”
  - Typical V_{OLP} (Output Ground Bounce) < 1.0V at V_{CC} = 5V, T_A = 25°C
- **Features for FCT162601AT/CT/ET:**
  - Balanced Output Drivers: ±24mA
  - Reduced system switching noise
  - Typical V_{OLP} (Output Ground Bounce) < 0.6V at V_{CC} = 5V, T_A = 25°C

DESCRIPTION:

The FCT16601AT/CT/ET and FCT162601AT/CT/ET 18-bit registered transceivers are built using advanced dual metal CMOS technology. These high-speed, low-power 18-bit registered bus transceivers combine D-type latches and D-type flip-flops to allow data flow in either direction in a transparent, latched or clocked mode. Each direction has an independent latch enable, an independent clock with a clock enable, and an independent output enable. The package is organized with a flow-through signal pin organization to ease board layout. All inputs are designed with hysteresis for improved noise margin.

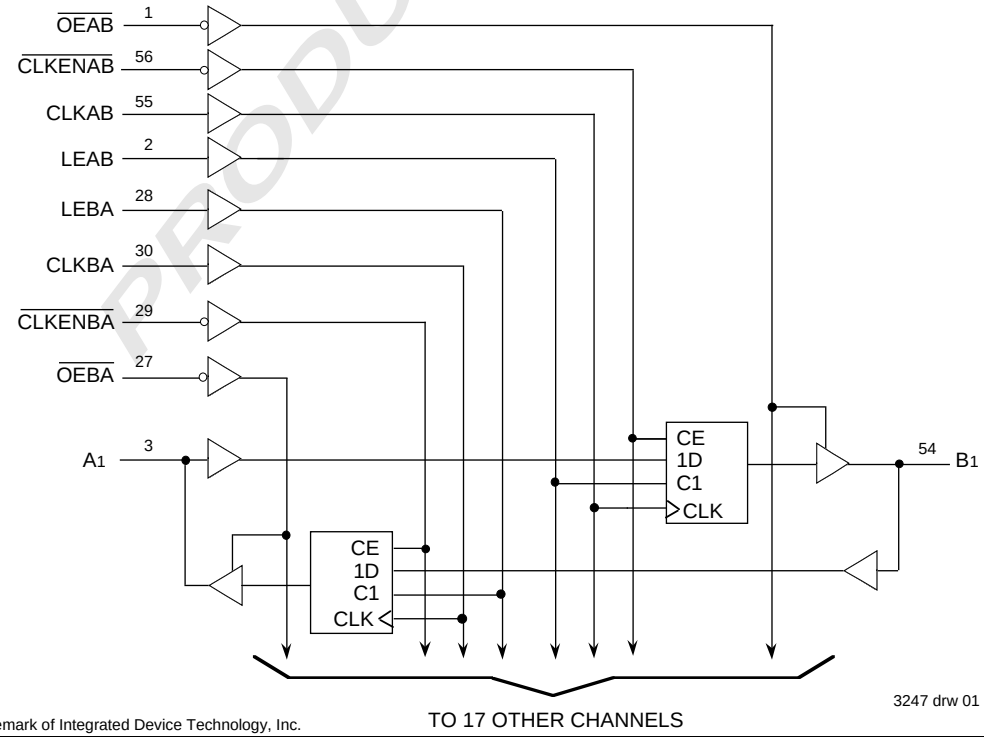
This transceiver is ideally suited for high speed memory interfaces which utilize high speed synchronous writes, by clocking the data into a high speed register. Reads can then be performed in a transparent or latched mode utilizing the same transceiver.

The FCT16601AT/CT/ET are ideally suited for driving high-capacitance loads and low-impedance backplanes. The output buffers are designed with power off disable capability to allow "live insertion" of boards when used as backplane drivers.

The FCT162601AT/CT/ET have balanced output drive with current limiting resistors. This offers low ground bounce, minimal undershoot, and controlled output fall times–reducing the need for external series terminating resistors. The FCT162601AT/CT/ET are plug-in replacements for the FCT16601AT/CT/ET and ABT16601 for on-board bus interface applications.

PRODUCT PREVIEW

FUNCTIONAL BLOCK DIAGRAM



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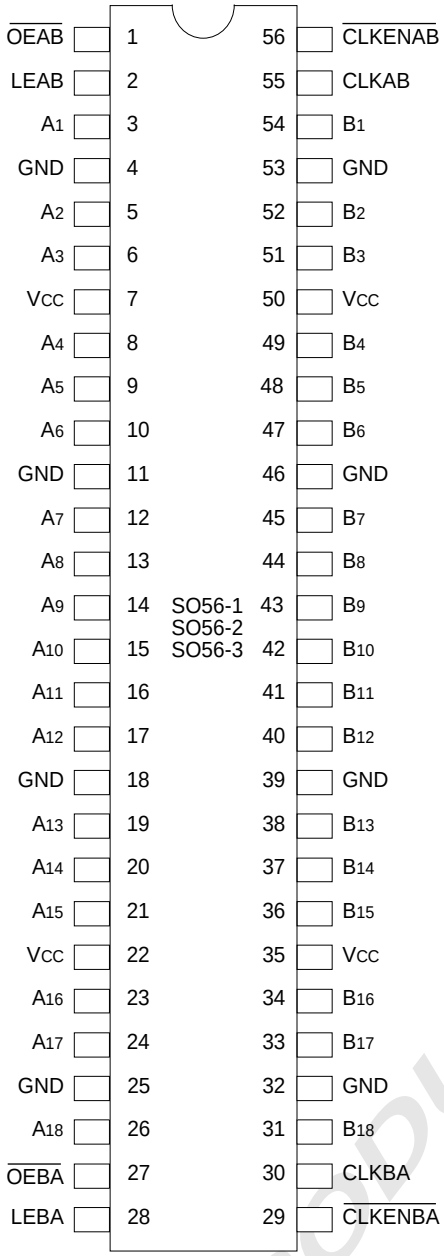
PIN CONFIGURATIONS



SSOP/ TSSOP/TVSOP TOP VIEW

3247 drw 02

PIN DESCRIPTION

Pin Names	Description
$\overline{OEAB}$	A-to-B Output Enable Input (Active LOW)
$\overline{OEBA}$	B-to-A Output Enable Input (Active LOW)
LEAB	A-to-B Latch Enable Input
LEBA	B-to-A Latch Enable Input
CLKAB	A-to-B Clock Input
CLKBA	B-to-A Clock Input
Ax	A-to-B Data Inputs or B-to-A 3-State Outputs
Bx	B-to-A Data Inputs or A-to-B 3-State Outputs
$\overline{CLKENAB}$	A to B Clock Enable Input
$\overline{CLKENBA}$	B to A Clock Enable Input

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ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Description	Max.	Unit
V_{TERM}(2)	Terminal Voltage with Respect to GND	–0.5 to +7.0	V
V_{TERM}(3)	Terminal Voltage with Respect to GND	–0.5 to V_{CC} +0.5	V
T_{STG}	Storage Temperature	–65 to +150	°C
I_{OUT}	DC Output Current	–60 to +120	mA

NOTES: 3247 lnk 03

1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. All device terminals except FCT162XXXT Output and I/O terminals.
3. Output and I/O terminals for FCT162XXXT.

CAPACITANCE (T_A = +25°C, f = 1.0MHz)

Symbol	Parameter(1)	Conditions	Typ.	Max.	Unit
C_{IN}	Input Capacitance	V_{IN} = 0V	3.5	6.0	pF
$C_{I/O}$	I/O Capacitance	V_{OUT} = 0V	3.5	8.0	pF

NOTE: 3247 lnk 04

1. This parameter is measured at characterization but not tested.

FUNCTION TABLE(1,4)

Inputs					Outputs
$\overline{CLKENAB}$	$\overline{OEAB}$	LEAB	CLKAB	A	B
X	H	X	X	X	Z
X	L	H	X	L	L
X	L	H	X	H	H
H	L	L	X	X	B0(2)
L	L	L	↑	L	L
L	L	L	↑	H	H
L	L	L	L	X	B0(2)
L	L	L	H	X	B0(3)

NOTES: 3247 tbl 02

1. A-to-B data flow is shown. B-to-A data flow is similar but uses $\overline{OEBA}$, LEBA and CLKBA.
2. Output level before the indicated steady-state input conditions were established.
3. Output level before the indicated steady-state input conditions were established, provided that CLKAB was HIGH before LEAB went LOW.
4. H = HIGH Voltage Level
   L = LOW Voltage Level
   X = Don't Care
   Z = High-impedance
   ↑ = LOW-to-HIGH Transition

PRODUCT PREVIEW

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:
Commercial: T_A = –40°C to +85°C, V_{CC} = 5.0V ± 10%

Symbol	Parameter	Test Conditions[1]		Min.	Typ.[2]	Max.	Unit
V_{IH}	Input HIGH Level	Guaranteed Logic HIGH Level		2.0	—	—	V
V_{IL}	Input LOW Level	Guaranteed Logic LOW Level		—	—	0.8	V
I_{IH}	Input HIGH Current (Input pins)	V_{CC} = Max.	V_I = V_{CC}	—	—	±1	µA
	Input HIGH Current (I/O pins)			—	—	±1	
I_{IL}	Input LOW Current (Input pins)		V_I = GND	—	—	±1	
	Input LOW Current (I/O pins)			—	—	±1	
I_{OZH}	High Impedance Output Current	V_{CC} = Max.	V_O = 2.7V	—	—	±1	µA
I_{OZL}	(3-State Output pins)		V_O = 0.5V	—	—	±1	
V_{IK}	Clamp Diode Voltage	V_{CC} = Min., I_{IN} = –18mA		—	–0.7	–1.2	V
I_{OS}	Short Circuit Current	V_{CC} = Max., V_O = GND[3]		–80	–140	–225	mA
V_H	Input Hysteresis	—		—	100	—	mV
I_{CCL} I_{CCH} I_{CCZ}	Quiescent Power Supply Current	V_{CC} = Max., V_{IN} = GND or V_{CC}		—	5	500	µA

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OUTPUT DRIVE CHARACTERISTICS FOR FCT16601T

Symbol	Parameter	Test Conditions[1]		Min.	Typ.[2]	Max.	Unit
I_O	Output Drive Current	V_{CC} = Max., V_O = 2.5V[3]		–50	—	–180	mA
V_{OH}	Output HIGH Voltage	V_{CC} = Min.	I_{OH} = –3mA	2.5	3.5	—	V
		V_{IN} = V_{IH} or V_{IL}	I_{OH} = –15mA	2.4	3.5	—	V
			I_{OH} = –32mA[4]	2.0	3.0	—	V
V_{OL}	Output LOW Voltage	V_{CC} = Min. V_{IN} = V_{IH} or V_{IL}	I_{OL} = 64mA	—	0.2	0.55	V
I_{OFF}	Input/Output Power Off Leakage	V_{CC} = 0V, V_{IN} or V_O ≤ 4.5V		—	—	±1	µA

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OUTPUT DRIVE CHARACTERISTICS FOR FCT162601T

Symbol	Parameter	Test Conditions[1]		Min.	Typ.[2]	Max.	Unit
I_{ODL}	Output LOW Current	V_{CC} = 5V, V_{IN} = V_{IH} or V_{IL}, V_{OUT} = 1.5V[3]		60	115	200	mA
I_{ODH}	Output HIGH Current	V_{CC} = 5V, V_{IN} = V_{IH} or V_{IL}, V_{OUT} = 1.5V[3]		–60	–115	–200	mA
V_{OH}	Output HIGH Voltage	V_{CC} = Min. V_{IN} = V_{IH} or V_{IL}	I_{OH} = –24mA	2.4	3.3	—	V
V_{OL}	Output LOW Voltage	V_{CC} = Min. V_{IN} = V_{IH} or V_{IL}	I_{OL} = 24mA	—	0.3	0.55	V

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NOTES:

1. For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type.
2. Typical values are at Vcc = 5.0V, +25°C ambient.
3. Not more than one output should be tested at one time. Duration of the test should not exceed one second.
4. Duration of the condition can not exceed one second.

PRODUCT PREVIEW

POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Conditions[1]		Min.	Typ.[2]	Max.	Unit
ΔI_{CC}	Quiescent Power Supply Current TTL Inputs HIGH	V_{CC} = Max. V_{IN} = 3.4V[3]		—	0.5	1.5	mA
I_{CCD}	Dynamic Power Supply Current[4]	V_{CC} = Max., Outputs Open $\overline{OEAB}$ = V_{CC} $\overline{OEBA}$ = GND One Input Toggling 50% Duty Cycle	V_{IN} = V_{CC} V_{IN} = GND	—	75	120	µA/ MHz
I_C	Total Power Supply Current[6]	V_{CC} = Max., Outputs Open f_{CP} = 10MHz (CLKBA) 50% Duty Cycle $\overline{OEAB}$ = V_{CC} $\overline{OEBA}$ = GND LEAB = GND $\overline{CLKENBA}$ = GND One Bit Toggling f_i = 5MHz 50% Duty Cycle	V_{IN} = V_{CC} V_{IN} = GND	—	0.8	1.7	mA
			V_{IN} = 3.4V V_{IN} = GND	—	1.3	3.2	
		V_{CC} = Max., Outputs Open f_{CP} = 10MHz (CLKBA) 50% Duty Cycle $\overline{OEAB}$ = V_{CC} $\overline{OEBA}$ = GND LEAB = GND $\overline{CLKENBA}$ = GND Eighteen Bits Toggling f_i = 2.5MHz 50% Duty Cycle	V_{IN} = V_{CC} V_{IN} = GND	—	3.8	6.5[5]	
			V_{IN} = 3.4V V_{IN} = GND	—	8.5	20.8[5]	

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NOTES:

1. For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type.
2. Typical values are at V_{CC} = 5.0V, +25°C ambient.
3. Per TTL driven input (V_{IN} = 3.4V). All other inputs at V_{CC} or GND.
4. This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.
5. Values for these conditions are examples of the I_{CC} formula. These limits are guaranteed but not tested.
6. $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$
   $I_C = I_{CC} + \Delta I_{CC} D_H N_T + I_{CCD} (f_{CP} N_{CP}/2 + f_i N_i)$
   I_{CC} = Quiescent Current (I_{CCL}, I_{CCH} and I_{CCZ})
   ΔI_{CC} = Power Supply Current for a TTL High Input (V_{IN} = 3.4V)
   D_H = Duty Cycle for TTL Inputs High
   N_T = Number of TTL Inputs at D_H
   I_{CCD} = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)
   f_{CP} = Clock Frequency for Register Devices (Zero for Non-Register Devices)
   N_{CP} = Number of Clock Inputs at f_{CP}
   f_i = Input Frequency
   N_i = Number of Inputs at f_i

PRODUCT PREVIEW

SWITCHING CHARACTERISTICS OVER OPERATING RANGE

Symbol	Parameter		Condition[1]	FCT16601AT/ FCT162601AT		FCT16601CT/ FCT162601CT		FCT16601ET/ FCT162601ET		Unit
				Min.[2]	Max.	Min.[2]	Max.	Min.[2]	Max.	
f_{MAX}	CLKAB or CLKBA frequency[4]		C_L = 50pF	—	150	—	150	—	150	MHz
t_{PLH} t_{PHL}	Propagation Delay Ax to Bx or Bx to Ax		R_L = 500Ω	1.5	4.9	1.5	4.4	1.5	3.8	ns
t_{PLH} t_{PHL}	Propagation Delay LEBA to Ax, LEAB to Bx			1.5	5.2	1.5	4.7	1.5	4.2	ns
t_{PLH} t_{PHL}	Propagation Delay CLKBA to Ax, CLKAB to Bx			1.5	4.7	1.5	4.5	1.5	4.2	ns
t_{PZH} t_{PZL}	Output Enable Time $\overline{OEBA}$ to Ax, $\overline{OEAB}$ to Bx			1.5	5.8	1.5	5.3	1.5	4.8	ns
t_{PHZ} t_{PLZ}	Output Disable Time $\overline{OEBA}$ to Ax, $\overline{OEAB}$ to Bx			1.5	6.2	1.5	5.7	1.5	5.2	ns
t_{SU}	Set-up Time, HIGH or LOW Ax to CLKAB, Bx to CLKBA			4.0	—	3.0	—	2.4	—	ns
t_H	Hold Time HIGH or LOW Ax after CLKAB, Bx after CLKBA			0	—	0	—	0	—	ns
t_{SU}	Set-up Time HIGH or LOW	Clock LOW		1.0	—	1.0	—	1.0	—	ns
	Ax to LEAB, Bx to LEBA	Clock HIGH		2.5	—	2.0	—	1.5	—	ns
t_H	Hold Time, HIGH or LOW Ax after LEAB, Bx after LEBA			2.0	—	1.5	—	0.5	—	ns
t_{SU}	Set-up Time, $\overline{CLKEN}$ to CLK			2.5	—	2.5	—	2.0	—	ns
t_H	Hold Time, $\overline{CKLEN}$ after CLK			0	—	0	—	0	—	ns
t_W	LEAB or LEBA Pulse Width HIGH[4]			2.5	—	2.5	—	2.5	—	ns
t_W	CLKAB or CLKBA Pulse Width HIGH or LOW[4]			3.0	—	3.0	—	3.0	—	ns
$t_{SK(o)}$	Output Skew[3]			—	0.5	—	0.5	—	0.5	ns

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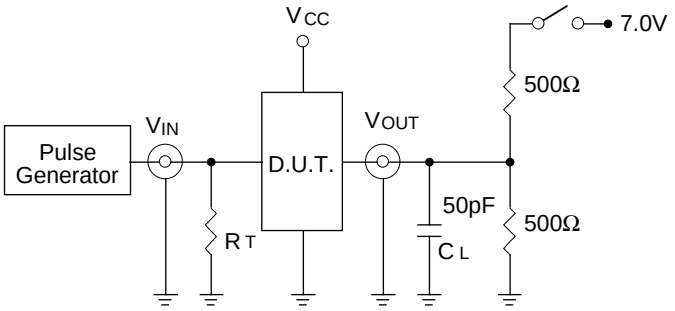
NOTES:
1. See test circuits and waveforms.
2. Minimum limits are guaranteed but not tested on Propagation Delays.
3. Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.
4. This parameter is guaranteed but not tested.

PRODUCT PREVIEW

TEST CIRCUITS AND WAVEFORMS

TEST CIRCUITS FOR ALL OUTPUTS



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SWITCH POSITION

Test	Switch
Open Drain Disable Low Enable Low	Closed
All Other Tests	Open

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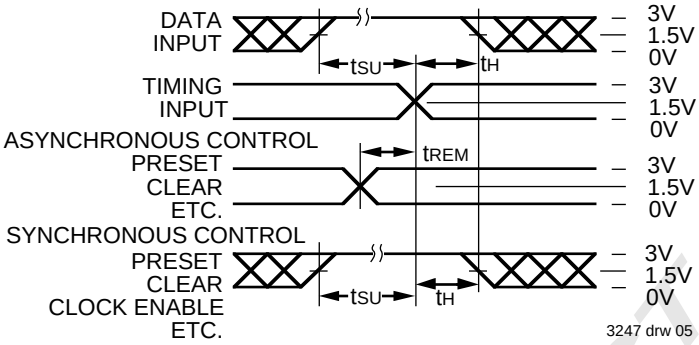
DEFINITIONS:

C_L= Load capacitance: includes jig and probe capacitance.
R_T = Termination resistance: should be equal to Z_{OUT} of the Pulse Generator.

SET-UP, HOLD AND RELEASE TIMES



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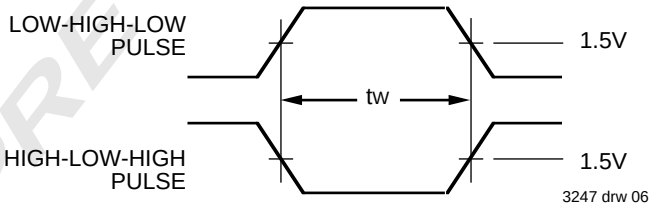
PULSE WIDTH



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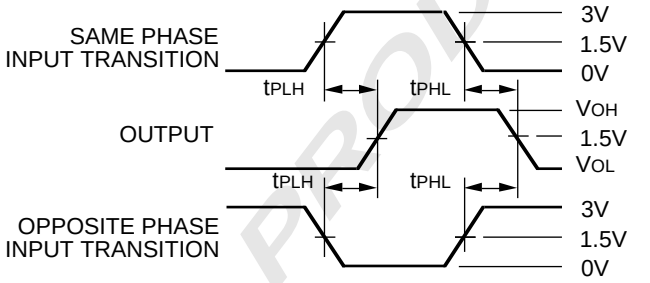
PROPAGATION DELAY



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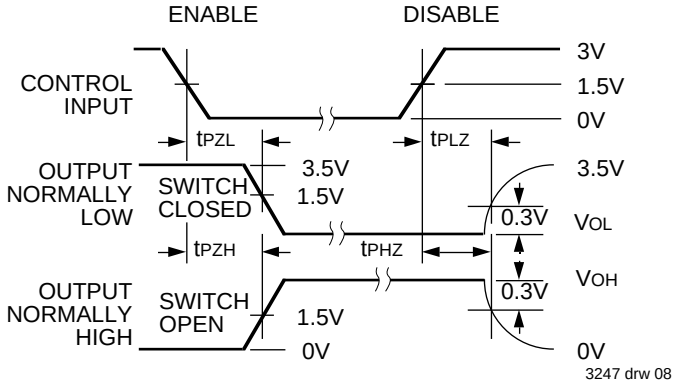
ENABLE AND DISABLE TIMES



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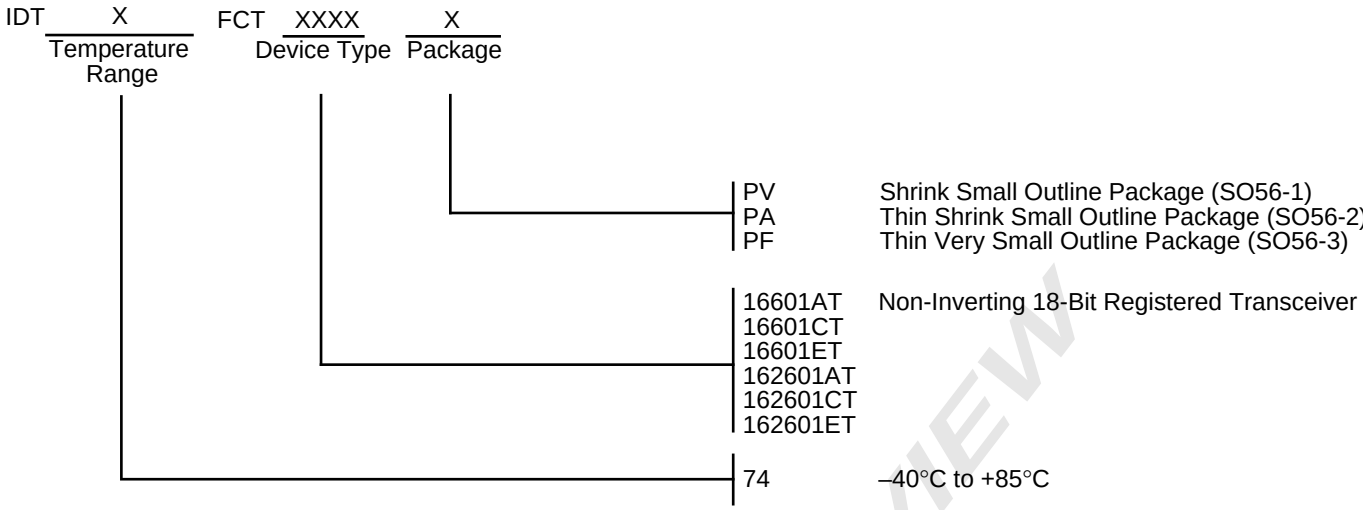
NOTES:

1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH
2. Pulse Generator for All Pulses: Rate ≤ 1.0MHz; t_F ≤ 2.5ns; t_R ≤ 2.5ns

PRODUCT PREVIEW

ORDERING INFORMATION



PRODUCT PREVIEW